

N-Channel 100 V (D-S) MOSFET

MOSFET PRODUCT SUMMARY			
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)
100	0.234 at V _{GS} = 10 V	2.3	2.9 nC
	0.267 at V _{GS} = 6 V	2.1	
	0.278 at V _{GS} = 4.5 V	1.7	

FEATURES

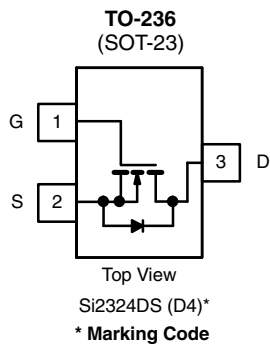
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested
- Material categorization:
For definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- DC/DC Converters
- Load Switch
- LED Backlighting in LCD TVs



Ordering Information:
Si2324DS-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)				
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	100	V	
Gate-Source Voltage	V _{GS}	± 20		
Continuous Drain Current (T _J = 150 °C)	I _D	T _C = 25 °C	2.3	
		T _C = 70 °C	1.8	
		T _A = 25 °C	1.6 ^{b, c}	
		T _A = 70 °C	1.3 ^{b, c}	
Pulsed Drain Current (t = 300 μs)	I _{DM}	5	A	
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C		2.1
		T _A = 25 °C		1.0 ^{b, c}
Single Pulse Avalanche Current	I _{AS}	5		mJ
Single Pulse Avalanche Energy	E _{AS}	1.25		
Maximum Power Dissipation	P _D	T _C = 25 °C	2.5	
		T _C = 70 °C	1.6	
		T _A = 25 °C	1.25 ^{b, c}	
		T _A = 70 °C	0.8 ^{b, c}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	R _{thJA}	75	100	°C/W
Maximum Junction-to-Foot (Drain)	R _{thJF}	40	50	

Notes:

- Based on T_C = 25 °C.
- Surface mounted on 1" x 1" FR4 board.
- t = 5 s.
- Maximum under steady state conditions is 166 °C/W.

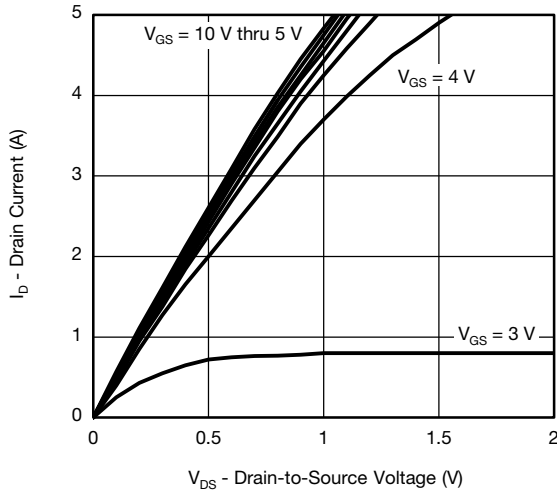
MOSFET SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{DS} = 0 V, I _D = 250 μA	100			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = 250 μA		105		mV/°C
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			- 5.2		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1.2		2.8	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			- 1	μA
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 55 °C			- 10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 4.5 V	5			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 1.5 A		0.195	0.234	Ω
		V _{GS} = 6 V, I _D = 1 A		0.222	0.267	
		V _{GS} = 4.5 V, I _D = 0.5 A		0.231	0.278	
Forward Transconductance ^a	g _{fs}	V _{DS} = 20 V, I _D = 1.5 A		2.0		S
Dynamic^b						
Input Capacitance	C _{iss}	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz		190		pF
Output Capacitance	C _{oss}			22		
Reverse Transfer Capacitance	C _{rss}			13		
Total Gate Charge	Q _g	V _{DS} = 50 V, V _{GS} = 10 V, I _D = 1.6 A		5.2	10.4	nC
		V _{DS} = 50 V, V _{GS} = 4.5 V, I _D = 1.6 A		2.9	5.8	
Gate-Source Charge	Q _{gs}			0.75		
Gate-Drain Charge	Q _{gd}			1.4		
Gate Resistance	R _g	f = 1 MHz	0.3	1.4	2.8	Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = 50 V, R _L = 39 Ω I _D = 1.3 A, V _{GEN} = 4.5 V, R _g = 1 Ω		30	45	ns
Rise Time	t _r			26	39	
Turn-Off Delay Time	t _{d(off)}			17	26	
Fall Time	t _f			12	20	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 50 V, R _L = 39 Ω I _D = 1.3 A, V _{GEN} = 10 V, R _g = 1 Ω		6	12	
Rise Time	t _r			10	20	
Turn-Off Delay Time	t _{d(off)}			10	20	
Fall Time	t _f			6	12	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 2.1	A
Pulse Diode Forward Current ^a	I _{SM}				- 20	
Body Diode Voltage	V _{SD}	I _S = 1.3 A		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = 1.3 A, dI/dt = 100 A/μs, T _J = 25 °C		22	33	ns
Body Diode Reverse Recovery Charge	Q _{rr}			21	32	nC
Reverse Recovery Fall Time	t _a			16		ns
Reverse Recovery Rise Time	t _b			6		

Notes:

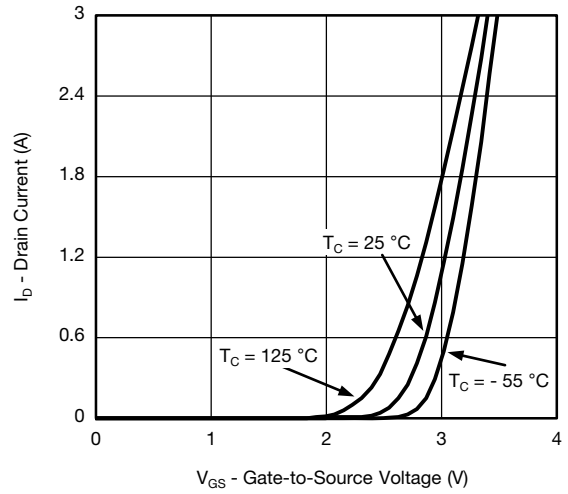
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

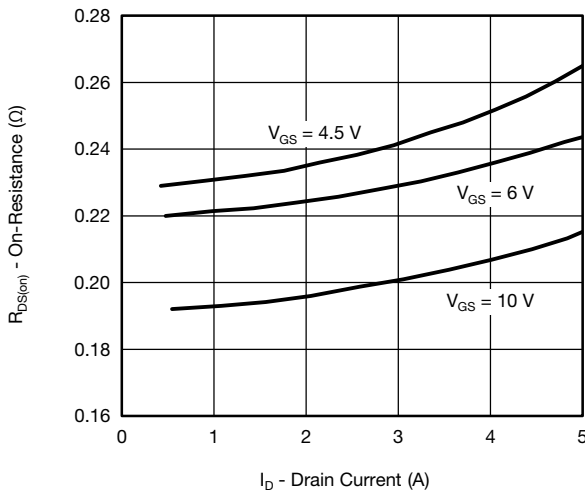
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



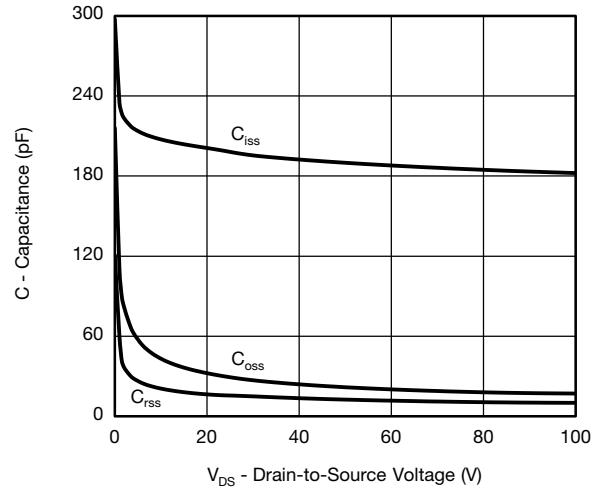
Output Characteristics



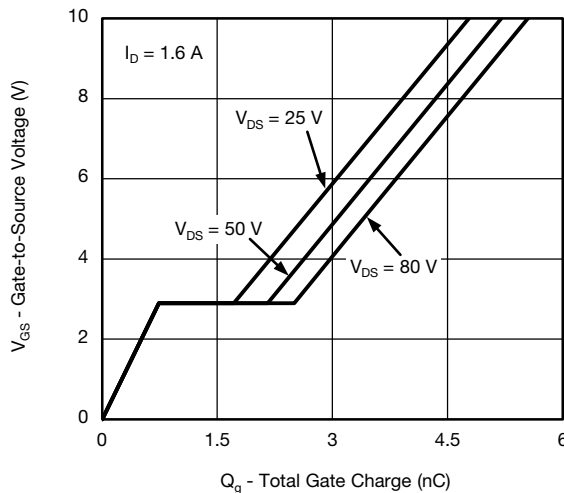
Transfer Characteristics



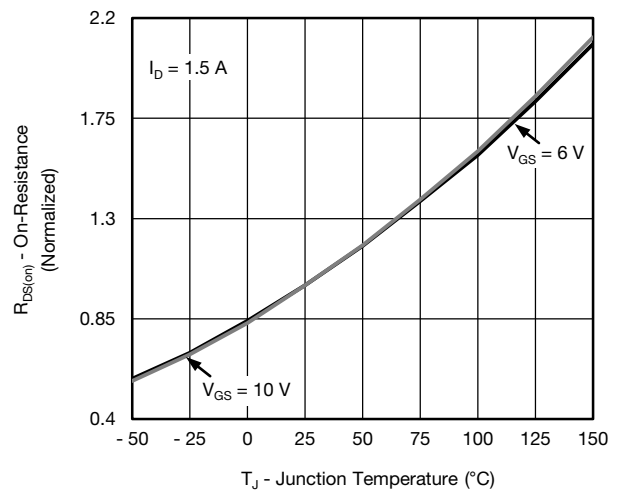
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

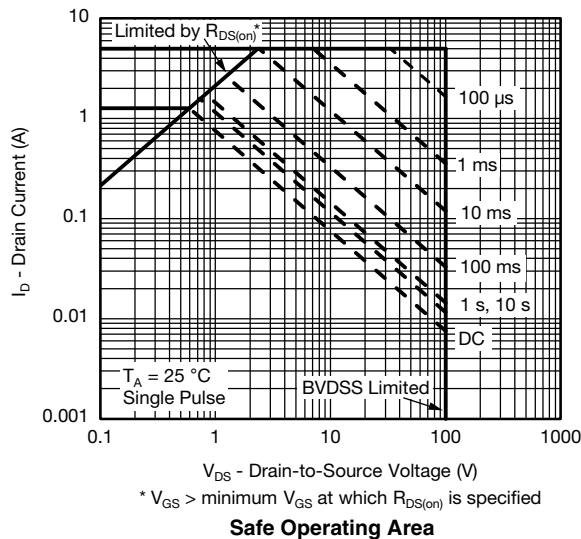
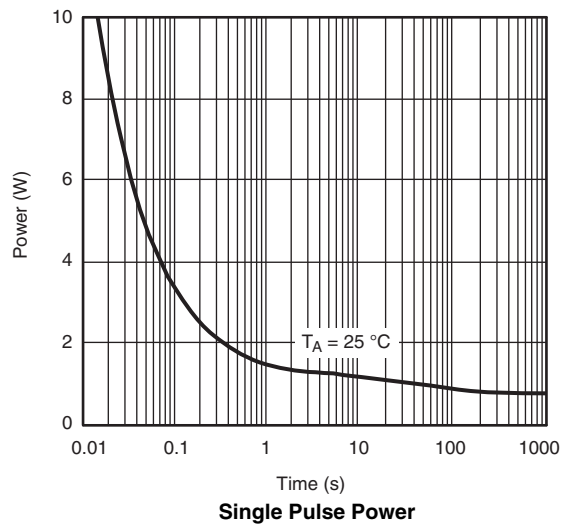
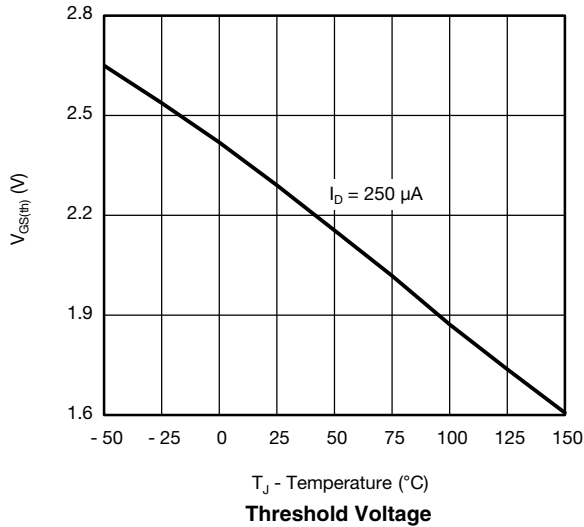
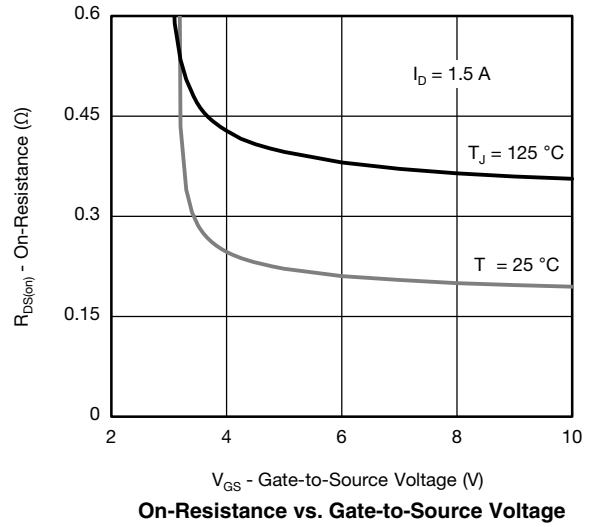
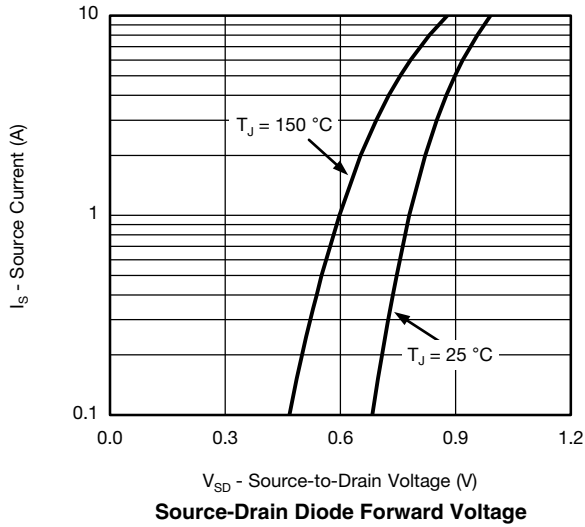


Gate Charge

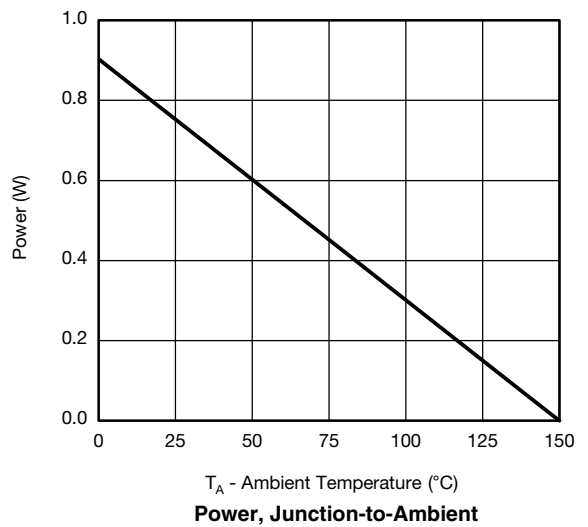
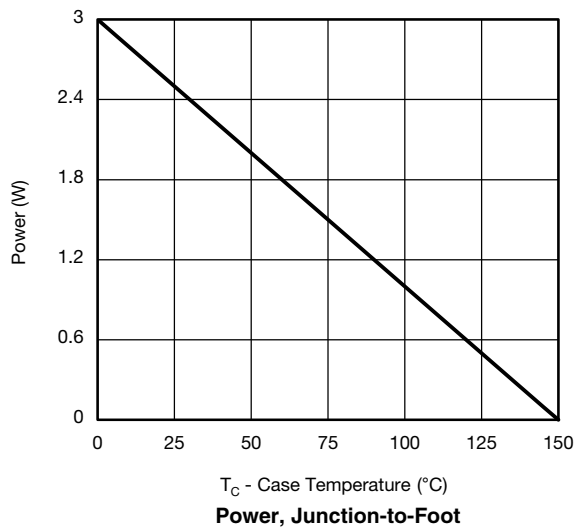
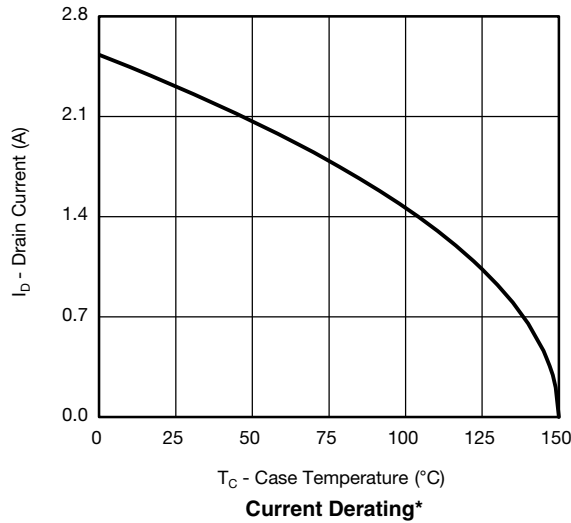


On-Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

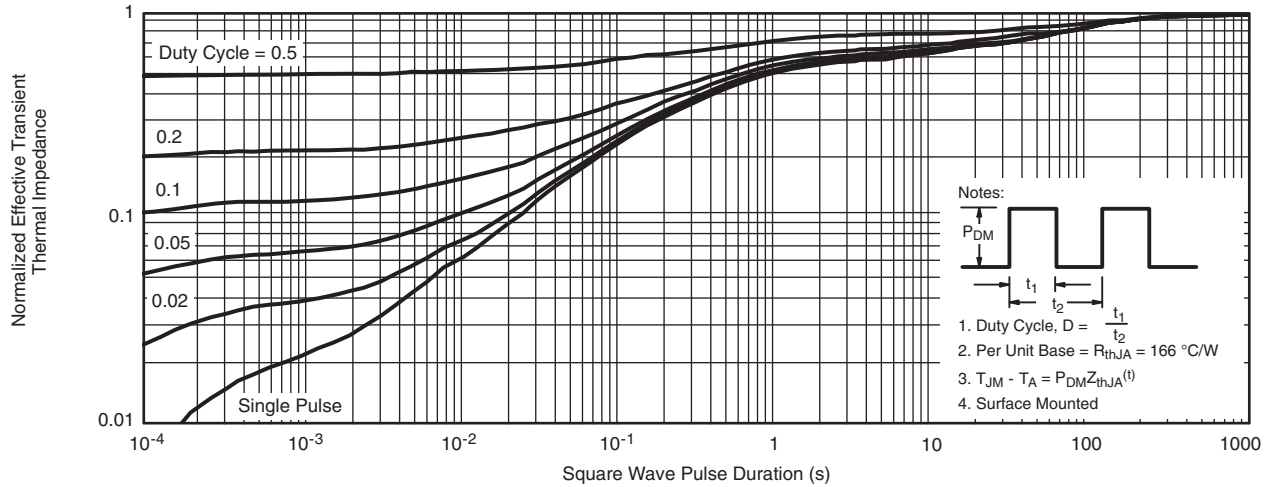


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

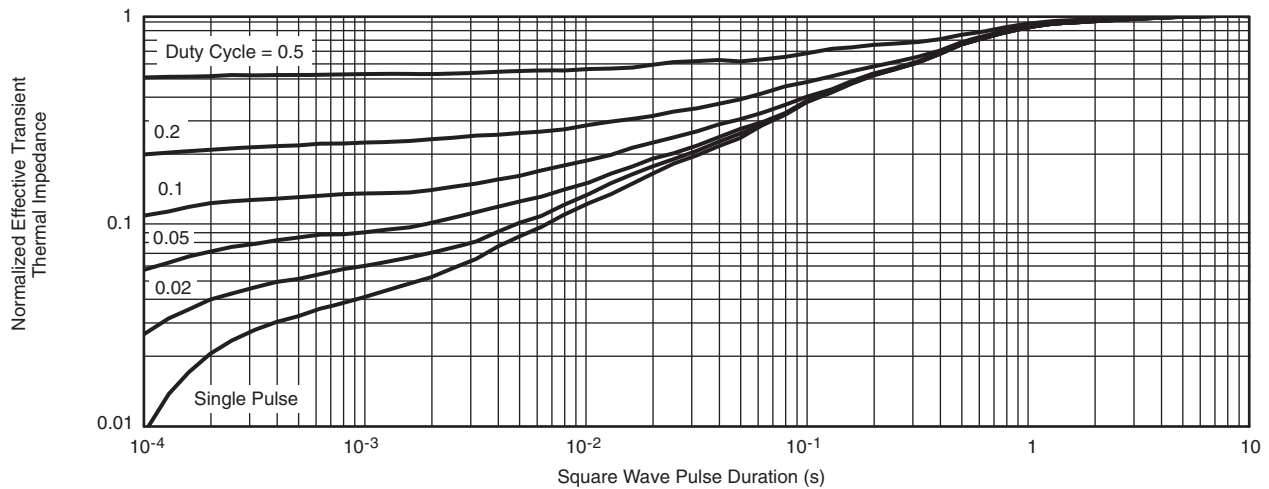


* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOT-23 (TO-236): 3-LEAD



Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	0.89	1.12	0.035	0.044
A ₁	0.01	0.10	0.0004	0.004
A ₂	0.88	1.02	0.0346	0.040
b	0.35	0.50	0.014	0.020
c	0.085	0.18	0.003	0.007
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.083	0.104
E ₁	1.20	1.40	0.047	0.055
e	0.95 BSC		0.0374 Ref	
e ₁	1.90 BSC		0.0748 Ref	
L	0.40	0.60	0.016	0.024
L ₁	0.64 Ref		0.025 Ref	
S	0.50 Ref		0.020 Ref	
q	3°	8°	3°	8°

ECN: S-03946-Rev. K, 09-Jul-01
 DWG: 5479

RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads
Dimensions in Inches/(mm)

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